



## Material Content Data Sheet



<b>Sales Product Name</b>		2ED020I12-F2		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001021436						
<b>Package</b>		PG-DSO-36-58		<b>Weight*</b>		629.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.549	0.72	0.72	7228	7228
leadframe	inorganic material	phosphorus	7723-14-0	0.055	0.01		88	
	non noble metal	zinc	7440-66-6	0.220	0.04		350	
	non noble metal	iron	7439-89-6	4.406	0.70		7002	
wire	non noble metal	copper	7440-50-8	178.916	28.43	29.18	284315	291755
	noble metal	gold	7440-57-5	1.255	0.20	0.20	1994	1994
	encapsulation	organic material	carbon black	1333-86-4	0.865	0.14		1374
plastics	plastics	epoxy resin	-	39.784	6.32		63221	
		silicondioxide	60676-86-0	391.790	62.27	68.73	622592	687187
leadfinish	non noble metal	tin	7440-31-5	4.296	0.68	0.68	6827	6827
plating	noble metal	silver	7440-22-4	1.022	0.16	0.16	1624	1624
glue	plastics	epoxy resin	-	0.533	0.08		846	
		noble metal	silver	7440-22-4	1.598	0.25	0.33	2539
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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